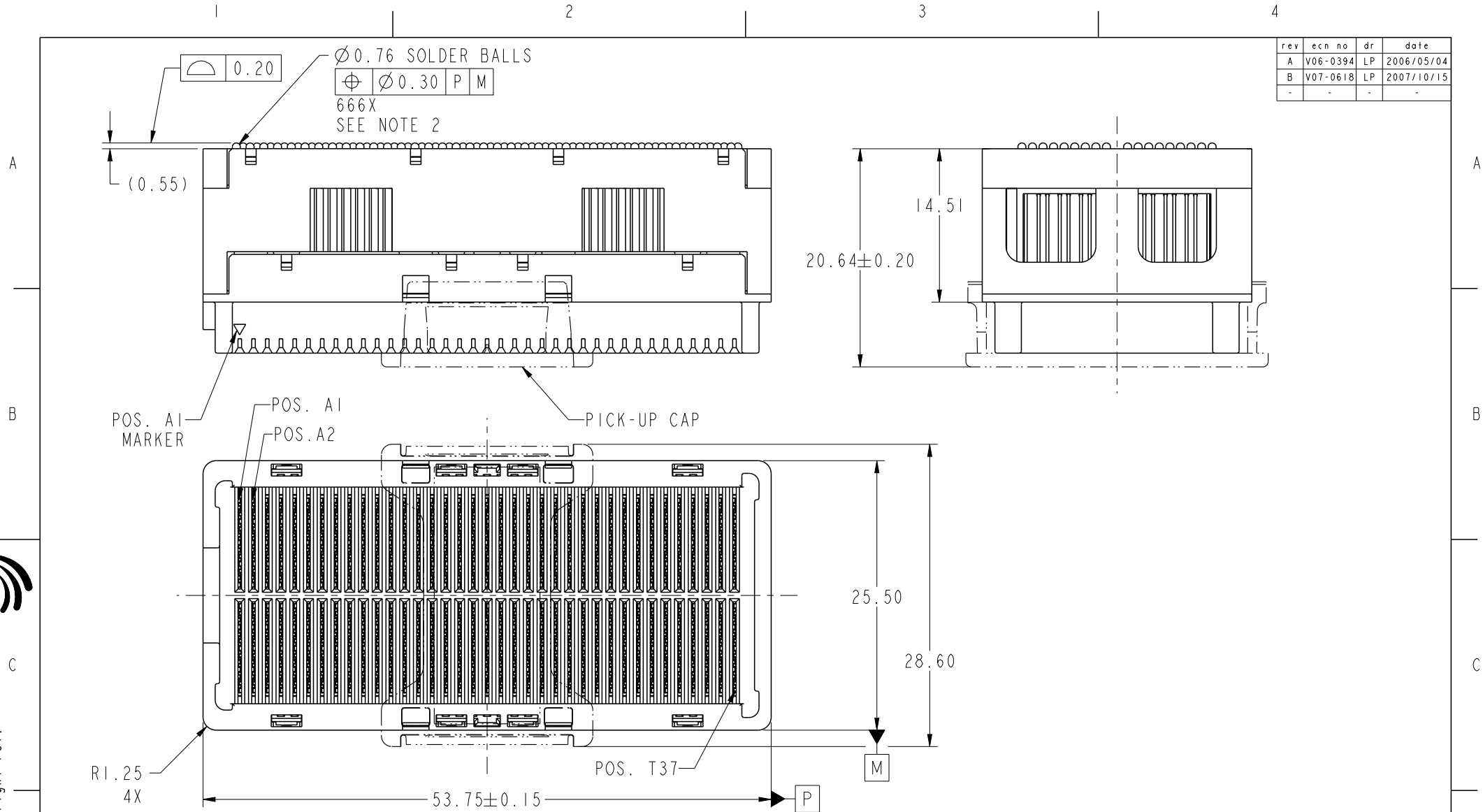
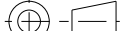


rev	ecn no	dr	date
A	V06-0394	LP	2006/05/04
B	V07-0618	LP	2007/10/15
-	-	-	-



spec ref		-		dr	Bill Lin	2010/02/02	projection 	mm 	size	A4	scale	1:1		
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Nickor Zuo	2011/06/15			ecn no	ELX-DG-003943-1				
				chr	Alex Cao	2011/06/24								
				appr	Pei-Ming Zheng	2011/06/27								
							product family		GIG-Array		rel level		Released	
surface		linear	0.X	±0.30		title	GIG-Array - LOW INSERTION			dwg no	10060913		rev	C
			0.XX	±0.10										
			0.XXX	±0.05										
ASME Y14.5	angular	0°	±2°	www.fci.com	cat. no.		-	Product - Customer Drw			sheet 1 of 5			

ProjE File - REV C - 2009-06-09

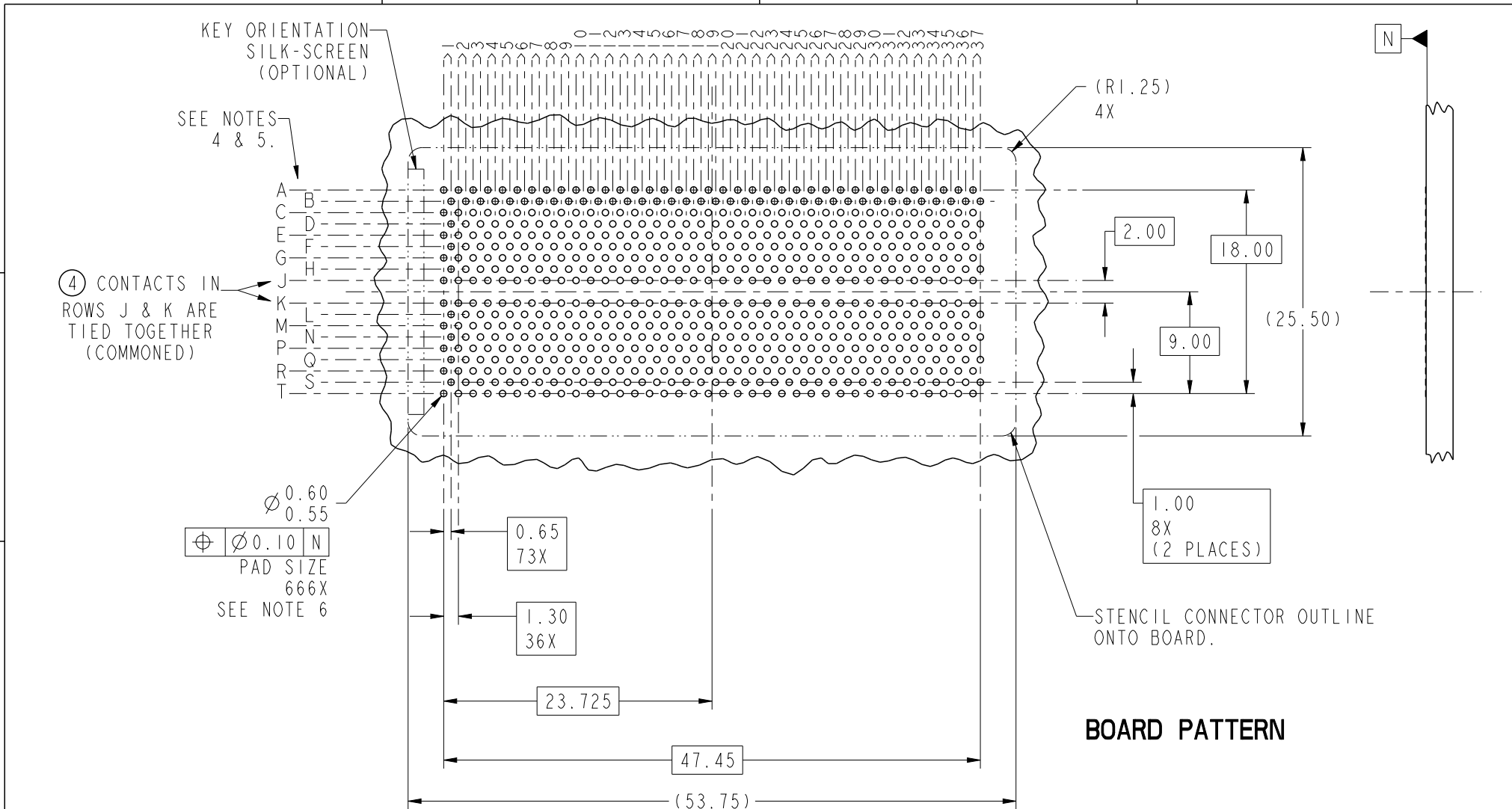
PDS: Rev :C

STATUS:Released

Printed: Jun 27, 2011



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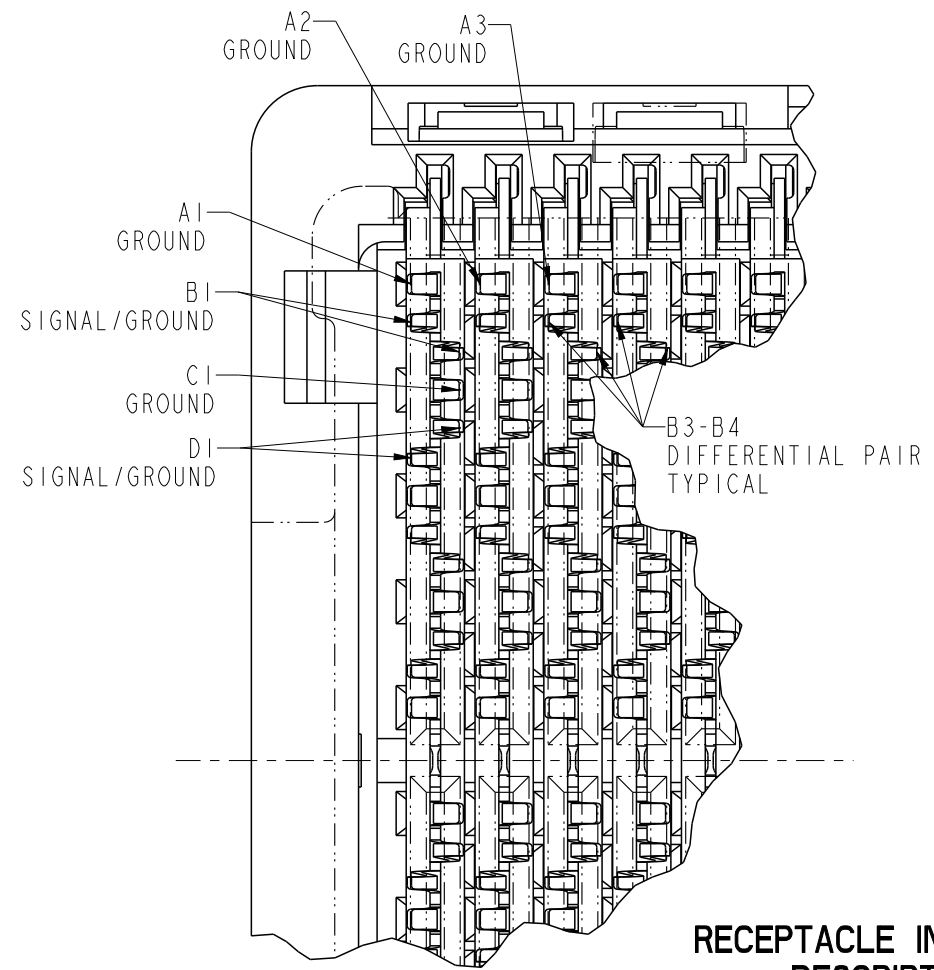


spec ref -				dr Bill Lin 2010/02/02		projection	mm	size A4	scale 1:1
tolerance std : -	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng Nickor Zuo 2011/06/15				ecn no ELX-DG-003943-1	
				chr Alex Cao 2011/06/24					
				appr Pei-Ming Zheng 2011/06/27					
product family GIG-Array						rel level Released			
surface 3.2	linear	0.X	±0.30		title GIG-Array - LOW INSERTION 15mm RECP. ASSY. 296 SIG. POS.		dwg no 10060913	rev C	
		0.XX	±0.10						
		0.XXX	±0.05						
ASME Y14.5	angular	0°	±2°	www.fci.com	cat. no. -	Product - Customer Drw		sheet 2 of 5	

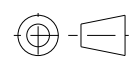
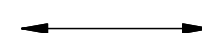
Print File - REV C - 2009-06-09



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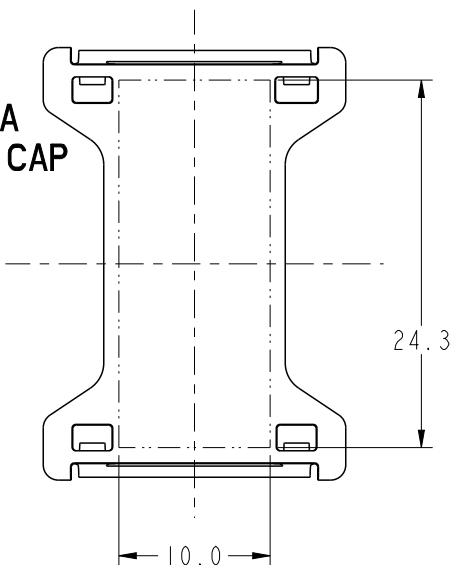


RECEPTACLE INTERFACE DESCRIPTION

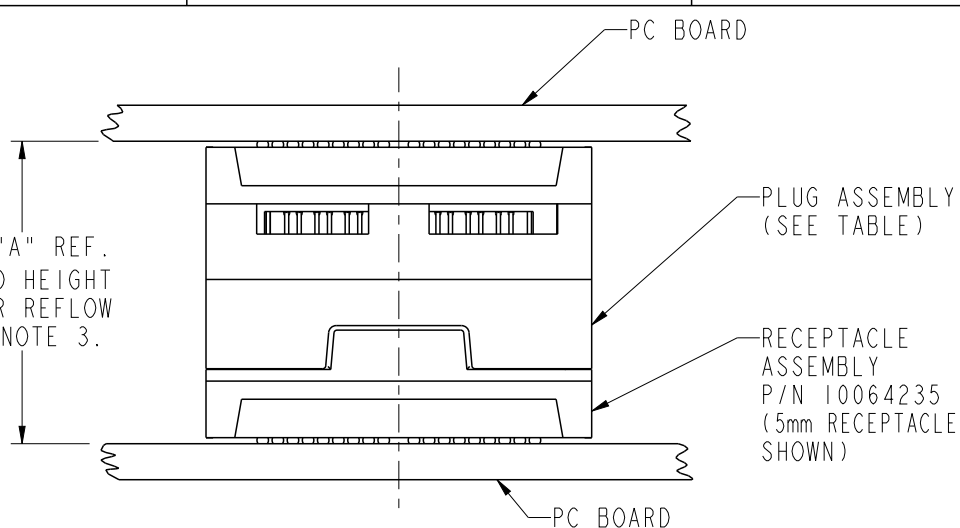
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tolerance std : -	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Nickor Zuo	2011/06/15			ecn no				ELX-DG-003943-1
				chr	Alex Cao	2011/06/24			rel level				Released
				appr	Pei-Ming Zheng	2011/06/27			product family		GIG-Array		
surface 3.2 √ ASME Y14.5	linear	0.X	±0.30		title GIG-Array - LOW INSERTION 15mm RECP. ASSY. 296 SIG. POS.			dwg no	10060913		rev C		
		0.XX	±0.10										
		0.XXX	±0.05										
angular		0°	±2°	www.fci.com	cat. no.		-	Product - Customer Drw			sheet 3 of 5		

ProjE File - REV C - 2009-06-09

FLAT AREA
FOR PICK-UP CAP
SCALE 2:1



DIM "A" REF.
MATED HEIGHT
AFTER REFLOW
SEE NOTE 3.



END VIEW OF MATED CONNECTORS
SCALE 2:1

DIM. "A"	PLUG ASSEMBLY P/N
25	55720
27	10026804
28	10055143
30	55700
35	55727
40	10054784

spec ref -				dr Bill Lin		2010/02/02		projection		mm		size A4		scale 1:1			
tolerance std				eng Nickor Zuo		2011/06/15						ecn no ELX-DG-003943-1					
TOLERANCES UNLESS OTHERWISE SPECIFIED				chr Alex Cao		2011/06/24											
:				appr Pei-Ming Zheng		2011/06/27											
								product family GIG-Array				rel level Released					
surface 3.2		linear		0.X ±0.30				title GIG-Array - LOW INSERTION				dwg no 10060913				rev C	
				0.XX ±0.10													
				0.XXX ±0.05													
ASME Y14.5		angular		0° ±2°		www.fci.com		cat. no. -		Product - Customer Drw				sheet 4 of 5			

PRODUCT NUMBER	SOLDER BALL COMPOSITION	CONTACT PLATING PERFORMANCE LEVEL
10060913-001	STANDARD (EUTECTIC)	PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-12-192, INCLUDING TELCORDIA CENTRAL OFFICE
10060913-001LF	LEADFREE	
10060913-201	STANDARD (EUTECTIC)	
10060913-201LF	LEADFREE	

Au over Ni

NOTES:

- MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY
PLATING (CONTACT): Au OVER Ni.
UL RATING: 94 V-0
SOLDERBALL: (SEE TABLE) EUTECTIC SnPb OR LEAD FREE 95.5 Sn/4Ag/0.5Cu.
- SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- MATED HEIGHT EFFECTED BY CUSTOMERS' PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTE.
- CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS USED AS GROUND PINS.
(NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])
- CONTACTS IN ROWS B,D,F,H,L,N,Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.
- SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE DOC. NO. GS-20-016.
- FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
- THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

spec ref -				dr Bill Lin		2010/02/02		projection		mm		size A4		scale 1:1	
tolerance std				eng Nickor Zuo		2011/06/15						ecn no ELX-DG-003943-1			
TOLERANCES UNLESS OTHERWISE SPECIFIED				chr Alex Cao		2011/06/24									
:				appr Pei-Ming Zheng		2011/06/27									
-								product family GIG-Array				rel level Released			
surface 3.2		linear		0.X ±0.30				title GIG-Array - LOW INSERTION				dwg no 10060913		rev C	
		0.XX ±0.10													
		0.XXX ±0.05													
ASME Y14.5		angular 0° ±2°		www.fci.com		cat. no. -		Product - Customer Drw				sheet 5 of 5			